

PPGA

Plastic Pin Grid Array Package (PPGA)

Amkor Technology incorporates the most advanced assembly processes for today and tomorrow's cost/performance applications. This IC package technology allows application and design engineers to optimize innovations while maximizing the performance characteristics of semiconductors (silicon & GaAs). PPGAs are designed for low inductance, improved thermal operation and enhanced capability. Custom performance enhancements, such as ground and power planes, are available for significant improvements in electrical response demanded by advancing electronics. Additionally, these PPGAs utilize industry proven, semiconductor grade materials for reliable, long-term operation while providing the user flexible design parameters. The PPGA is a laminate package. It consist typically of a Bt (Bismaleimide-Triazine) substrate which is covered with a B-Staged epoxy lid or by encapsulating it.

Applications:

Semiconductor technologies find enhanced performance by using the integrated design features of Amkor's PPGAs. Microprocessors / controllers, ASICs, Gate Arrays, memory, DSPs and PC chip sets find Amkor's PPGA family to be an ideal package. Applications requiring improved portability, form-factor/size and high-performance such as desk PCs, laptop PC's, and other similar products benefit from Amkor's PPGA attributes.

Features:

The PPGA offers a variety of features. From innovative designs and expanding package offerings, Amkor provides a platform from prototype-to-production:

- Flexible pin counts
- Heat plate / slug
- Variety of body sizes
- 50 mil & 100 mil pin pitch
- Perimeter, stagger and full pin arrays
- Multi-layer, ground / power
- Cavity Up and Cavity Down configurations available
- Cavity lid seal or encapsulation